Response to September 17, 2008 Non-Final Office Action

## **AMENDMENTS TO THE SPECIFICATION**

Docket No.: 20289/0204155-US0

Please replace the current chart with the following chart that appears on page 16 of the specification.

Tetracarboxylic acid component	Diamine component
BPDA  3.3'-4.4'-biphenylletracarboxylic dianhyddide 100 mol%	H <sub>2</sub> N — NH <sub>2</sub> PDA  p-phenylenediarune 100 mol%
BPDA 100 mol %	DAPE 4.4'-draminodiphenyl ether 100 mol%
PMDA pyromellilic dianhydride 100 mol%	H₂N → NH₂  PDA 100 mol%
PMDA 0	H <sub>2</sub> N
BPDA 100 mol*	H <sub>2</sub> N — NH <sub>2</sub> H <sub>2</sub> N — O — NH <sub>2</sub> PDA DAPE 75 mol % 25 mol %
PMDA	H <sub>2</sub> N — NH <sub>2</sub> H <sub>2</sub> N — O — NH <sub>2</sub> PDA DAPE  x mol % 100-x mol %
BPDA PMDA x mo!% 100-x mo!%	H <sub>2</sub> N — NH <sub>2</sub> PDA 100 mo l %
BPDA PMDA x mol%	H <sub>2</sub> N
BPDA PMDA x mol% 100-x mol%	H <sub>2</sub> N — NH <sub>2</sub> H <sub>2</sub> N — O — NH <sub>2</sub> PDA DAPE x mo   % 100-x mo   %

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Please replace the current paragraph 0032 with the following page 18, paragraph 32 in the

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specification.

In a method for using the adhesive aid composition of the present invention, preferably, the

polyimide precursor solution is applied to a substrate so that an imide film has a desired

thickness, and dried at 50°C to 150°C for 50 to 180 minutes to prepare a polyimide

precursor film. Furthermore On top of that, the adhesive aid composition of the present

invention is applied to the precursor film, dried at 50°C to 150°C for 5 to 180 minutes, and

then the polyimide precursor is subjected to imidization by heating at 200°C to 500°C for 20

to 300 minutes in a nitrogen stream to prepare a surface-adhesive film. In a system

containing the polyimide precursor, a catalyst and a dehydrator, imidization can be

performed at a lower temperature or within a shorter time. The resultant film of the present

invention is used together with the substrate or after being separated from the substrate.

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